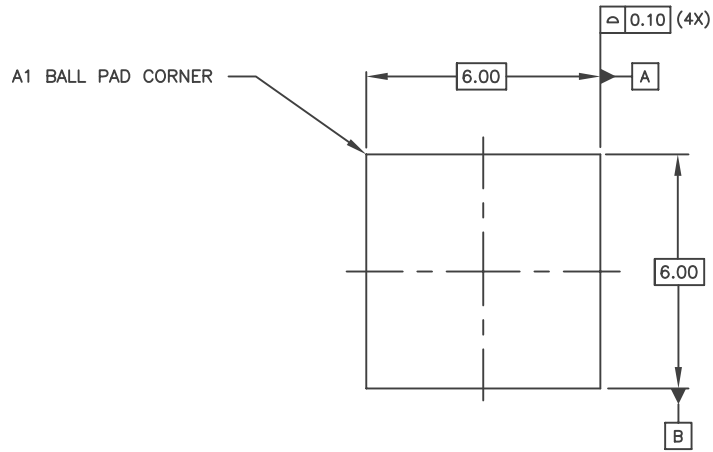
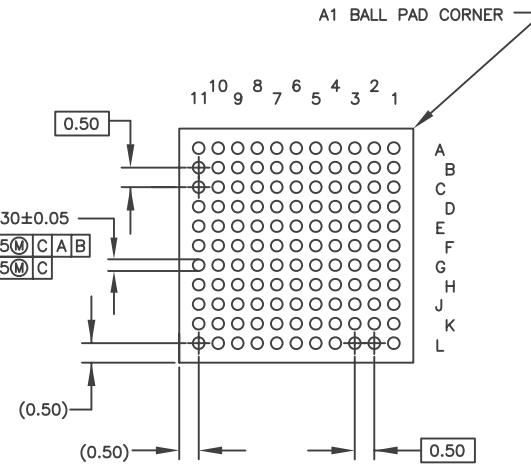


REVISIONS

ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
	A		NEW RELEASE	04/26/07	RUTH LIN
	B		REFORMAT, MOVE SOLDER BALL SIZE AT BGA BALL MATRIX	05/29/07	RUTH LIN
	C		REVISE ORIENTATION OF SIDE VIEW DIMENSIONS	01/14/08	D. GASTELUM

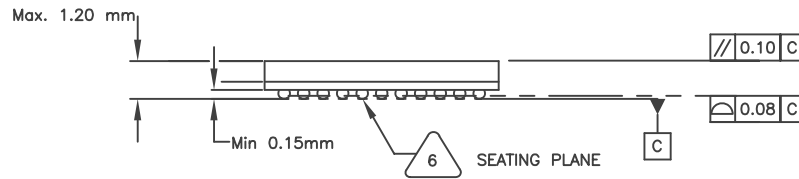


TOP VIEW



BOTTOM VIEW

121 SOLDER BALLS



SIDE VIEW

- 6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
- 4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 121.
- 3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 11 X 11.
- 2. THE BASIC SOLDER BALL GRID PITCH IS 0.50mm.
- 1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

DRAWN RUTH LIN	DATE 04/26/07				
APPROVED BY K.H. THE	DATE 04/26/07				
		TF-BGA, 6x6x1.20mm 2L, PU121 BALL, 0.50mm PITCH			
REFERENCE PACKAGE OUTLINES		PROJECTION 	SCALE N/A	DWG NO 03-015-67	REV C
QUICKLOGIC PKG CODE: PU121			SHEET 1 OF 1		